

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>YUNG-HSU WU</td> <td>11/11/2013</td> </tr> <tr> <td>CHIEN-HUA HUANG</td> <td>11/11/2013</td> </tr> <tr> <td>CHUNG-JU LEE</td> <td>11/13/2013</td> </tr> <tr> <td>TIEN-I BAO</td> <td>11/13/2013</td> </tr> <tr> <td>SHAU-LIN SHUE</td> <td>11/12/2013</td> </tr> </tbody> </table>		Name	Execution Date	YUNG-HSU WU	11/11/2013	CHIEN-HUA HUANG	11/11/2013	CHUNG-JU LEE	11/13/2013	TIEN-I BAO	11/13/2013	SHAU-LIN SHUE	11/12/2013
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RECEIVING PARTY DATA													
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.												
Street Address:	No. 8, Li-Hsin Rd. 6												
Internal Address:	Science-Based Industrial Park												
City:	Hsin-Chu												
State/Country:	TAIWAN												
Postal Code:	300-77 R.O.C.												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14081752</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14081752								
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Application Number:	14081752												
CORRESPONDENCE DATA													
Fax Number:	(972)732-9218												
Phone:	972-732-1001												
Email:	docketing@slater-matsil.com												
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>													
Correspondent Name:	SLATER & MATSIL, L.L.P.												
Address Line 1:	17950 PRESTON ROAD												
Address Line 2:	SUITE 1000												
Address Line 4:	DALLAS, TEXAS 75252												
ATTORNEY DOCKET NUMBER:	TSM13-1195												

502571631

PATENT
 REEL: 031615 FRAME: 0484

CH \$40.00 14081752

NAME OF SUBMITTER:	KASEY EDWARDS
Signature:	/Kasey Edwards/
Date:	11/15/2013
Total Attachments: 2 source=TSM13-1195_Assignment#page1.tif source=TSM13-1195_Assignment#page2.tif	

ATTORNEY DOCKET NO.
TSM13-1195

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of , with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Semiconductor Device having Voids and Method of Forming Same			
SIGNATURE OF INVENTOR AND NAME	<i>Yung-Hsu Wu</i> Yung-Hsu Wu	<i>Chien-Hua Huang</i> Chien-Hua Huang	<i>Chung-Ju Lee</i> Chung-Ju Lee	<i>Tien-I Bao</i> Tien-I Bao
DATE	<i>11/11, 2013</i>	<i>11/11, 2013</i>	<i>11/13, 2013</i>	<i>11/13, 2013</i>
RESIDENCE	Taipei City, Taiwan	Toufen Township, Taiwan	Hsin-Chu, Taiwan	Dayuan Township, Taiwan

ATTORNEY DOCKET NO. TSM13-1195

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and


WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of , with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

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IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Semiconductor Device having Voids and Method of Forming Same			
SIGNATURE OF INVENTOR AND NAME				
	Shau-Lin Shue			
DATE	2013. 11. 12			
RESIDENCE	Hsin-Chu, Taiwan			